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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

: **Confirmation No.**

Akihisa HONGO et al.

: Docket No. 2001_0133A

Serial No. 09/762,582

: Group Art Unit 1741

Filed April 12, 2001

: Examiner Brian Mutschler

SUBSTRATE PLATING
METHOD AND APPARATUS

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

Sir:

In response to the Office Action of May 7, 2003, the period for response to which having been extended by three months to November 7, 2003, please amend the above-identified U.S. Patent Application as follows:

Amendments to the Abstract

Please amend the original abstract (page 46) as follows:

ABSTRACT

The present invention provides a A method and apparatus plate for plating a substrate to form wiring by efficiently filling a fine recess (42) formed in a semiconductor substrate (~~W~~) with plating metal without a void or contamination. ~~The method for the plating of the~~ a substrate to fill a wiring recess formed in a the semiconductor substrate with plating metal (43) ~~comprises~~ includes performing an electroless plating process of forming an initial layer (41) on the a substrate (~~W~~), and performing an electrolytic plating process of filling the wiring recess with the plating metal, while the initial layer serves as a feeding layer.